



WaferBOND® CR-200

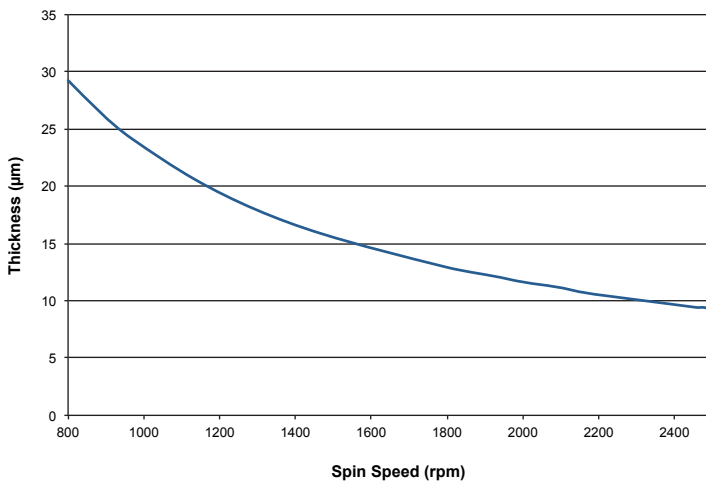
Temporary Bonding Material

WaferBOND® CR-200 temporary bonding material enables back-end-of-line processing of ultrathin wafers with standard semiconductor equipment.

BENEFITS

- Process ultrathin wafers using standard lithographic, passivation, and metallization techniques and tooling
- Create interconnects before or after thinning
- Preserve delicate structures on III-V devices

Spin Speed Curve



PROCESSING

Best known methods

20-µm process	
Coat	
Spin speed	1200 rpm
Acceleration	3000 rpm/s
Time	30 s
Bake	
Bake 1	120°C, 3 min
Bake 2	180°C, 4 min
Bond	
Temperature	180°C
Force	3500 N
Time	2 min
Vacuum	≤ 5 mbar

Storage Conditions

Store at room temperature (16° to 26° C)

Debonding Process (Two-Bath Process)

- Bath 1: Submerge in WaferBOND® Remover material at 110° to 130° C for 1 to 4 hours, or until debonded.
- Bath 2: Clean up with WaferBOND® Remover material at 70° to 110° C for 15 minutes to 1 hour. Mild circulation is recommended.
- Rinse: Isopropanol (IPA)
- Dry

Note: The flash point of WaferBOND® Remover material is 77° C. Please ensure that adequate engineering controls are in place before heating WaferBOND® Remover material above this temperature.

Resistance to Process Chemicals

Chemistry	Bath Temp.	Time
Acetone	25°C	25 min
NMP	85°C	60 min
6N HCl	60°C	30 min
15% H ₂ O ₂	60°C	40 min
30% NH ₄ OH	25°C	30 min
10% KI in H ₂ O	25°C	20 min
Ethanol	25°C	5 min
Methanol	25°C	5 min
Isopropanol	25°C	5 min
Cyclohexanone	25°C	5 min
Ethyl Lactate	25°C	5 min
PGMEA	25°C	5 min
PGME	25°C	5 min
30% HCl	25°C	90 min
70% HNO ₃	25°C	60 min
Note: An HMDS pretreatment is recommended for the following exposure recipes:		
0.26N TMAH	60°C	30 min
30% KOH	85°C	60 min

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